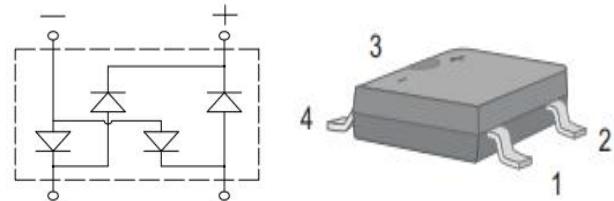


**Bridge Rectifier Diode 整流桥****■Features 特点**

Glass passivated chip junction 玻璃钝化结  
 High surge current capability 高浪涌电流能力  
 Reflow Solder Temperature 220°C 回流焊温度 220 度  
 Package 封装: ABS

**■Maximum Rating 最大额定值**

(TA=25°C unless otherwise noted 如无特殊说明, 温度为 25°C)

Characteristic 特性参数	Symbol 符号	FBS205	FBS21	FBS22	FBS24	FBS26	FBS28	FBS210	Unit 单位
Peak Reverse Voltage 反向峰值电压	V <sub>RRM</sub>	50	100	200	400	600	800	1000	V
DC Reverse Voltage 直流反向电压	V <sub>R(DC)</sub>	50	100	200	400	600	800	1000	V
RMS Reverse Voltage 反向电压均方根值	V <sub>R(RMS)</sub>	35	70	140	280	420	560	700	V
Reverse Recovery Time 反向恢复时间	T <sub>RR</sub>	150				350	500		nS
Forward Rectified Current 正向整流电流	I <sub>F</sub>	2						A	
Peak Surge Current 峰值浪涌电流	I <sub>FSM</sub>	70						A	
Thermal Resistance J-A 结到环境热阻	R <sub>θJA</sub>	75						°C/W	
Junction and Storage Temperature 结温和储藏温度	T <sub>J</sub> , T <sub>stg</sub>	150°C, -55 to +150°C							

**■Electrical Characteristics 电特性**

(TA=25°C unless otherwise noted 如无特殊说明, 温度为 25°C)

Characteristic 特性参数	Symbol 符号	Min 最小值	Typ 典型值	Max 最大值	Unit 单位	Condition 条件
Forward Voltage 正向电压降	V <sub>F</sub>		1.3		V	I <sub>F</sub> =1A
Reverse Current (TA=25°C) 反向漏电流(TA=100°C)	I <sub>R</sub>			5 200	uA	V <sub>R</sub> =V <sub>RRM</sub>
Diode Capacitance 二极管电容	C <sub>D</sub>		15		pF	V <sub>R</sub> =4V, f=1MHz

■Typical Characteristic Curve 典型特性曲线

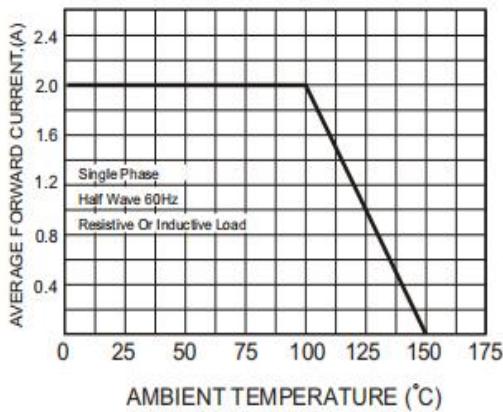


Figure 1: Forward Current Derating Curve

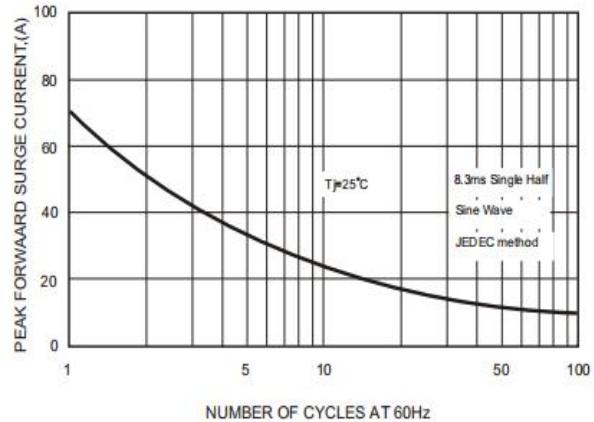


Figure 2: Peak Forward Surge Current

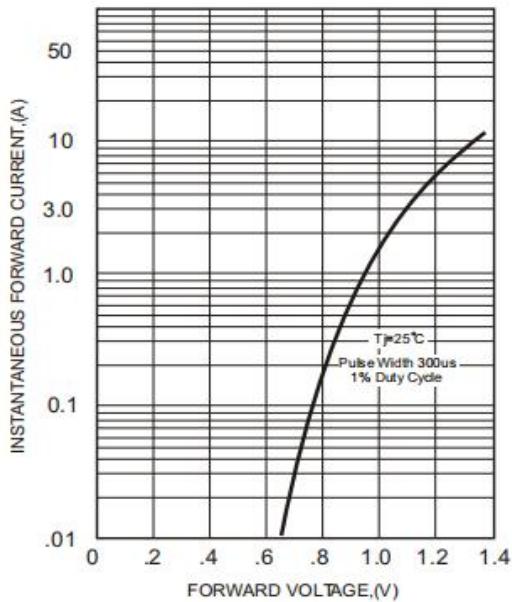


Figure 3: Instantaneous Forward Characteristics

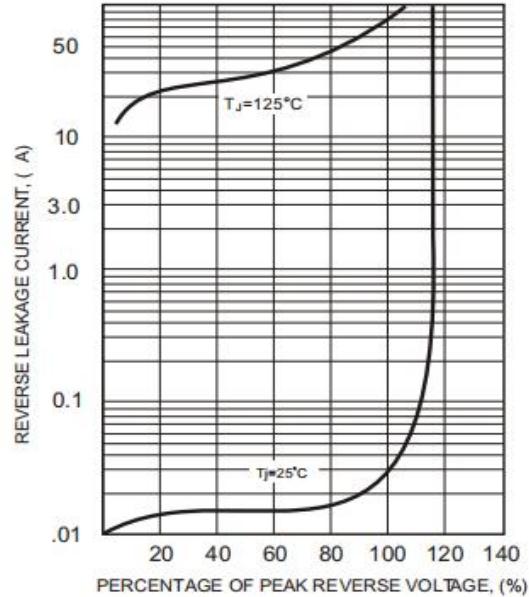
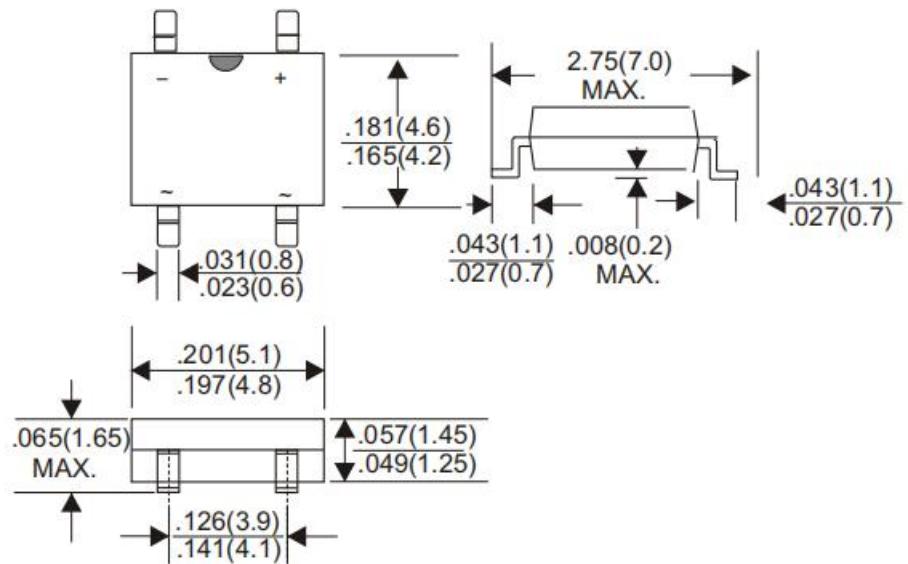


Figure 4: Reverse Leakage Characteristics

■ Dimension 外形封装尺寸

**ABS**



Dimensions in inches and (millimeters)